

CD54HC173, CD74HC173, CD54HCT173, CD74HCT173

High-Speed CMOS Logic Quad D-Type Flip-Flop, Three-State

Features

- Three-State Buffered Outputs
- Gated Input and Output Enables
- Fanout (Over Temperature Range)
 - Standard Outputs 10 LSTTL Loads
 - Bus Driver Outputs 15 LSTTL Loads
- Wide Operating Temperature Range . . . -55°C to 125°C
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types
 - 2V to 6V Operation
 - High Noise Immunity: $N_{IL} = 30\%$, $N_{IH} = 30\%$ of V_{CC} at $V_{CC} = 5V$
- HCT Types
 - 4.5V to 5.5V Operation
 - Direct LSTTL Input Logic Compatibility, $V_{IL} = 0.8V$ (Max), $V_{IH} = 2V$ (Min)
 - CMOS Input Compatibility, $I_I \leq 1\mu A$ at V_{OL} , V_{OH}

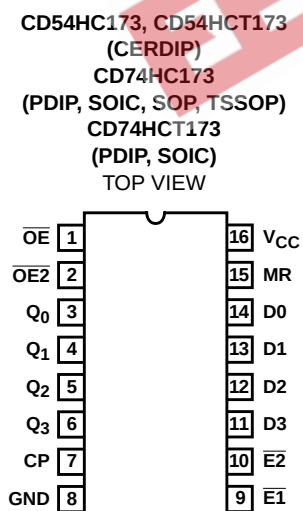
Description

The 'HC173 and 'HCT173 high speed three-state quad D-type flip-flops are fabricated with silicon gate CMOS technology. They possess the low power consumption of standard CMOS Integrated circuits, and can operate at speeds comparable to the equivalent low power Schottky devices. The buffered outputs can drive 15 LSTTL loads. The large output drive capability and three-state feature make these parts ideally suited for interfacing with bus lines in bus oriented systems.

The four D-type flip-flops operate synchronously from a common clock. The outputs are in the three-state mode when either of the two output disable pins are at the logic "1" level. The input ENABLES allow the flip-flops to remain in their present states without having to disrupt the clock. If either of the 2 input ENABLES are taken to a logic "1" level, the Q outputs are fed back to the inputs, forcing the flip-flops to remain in the same state. Reset is enabled by taking the MASTER RESET (MR) input to a logic "1" level. The data outputs change state on the positive going edge of the clock.

The 'HCT173 logic family is functionally, as well as pin compatible with the standard LS logic family.

Pinout



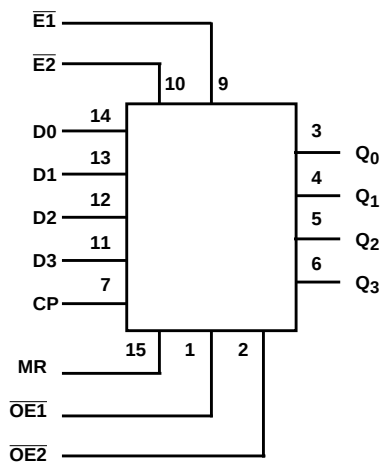
Ordering Information

PART NUMBER	TEMP. RANGE (°C)	PACKAGE
CD54HC173F3A	-55 to 125	16 Ld CERDIP
CD54HCT173F3A	-55 to 125	16 Ld CERDIP
CD74HC173E	-55 to 125	16 Ld PDIP
CD74HC173M	-55 to 125	16 Ld SOIC
CD74HC173MT	-55 to 125	16 Ld SOIC
CD74HC173M96	-55 to 125	16 Ld SOIC
CD74HC173NSR	-55 to 125	16 Ld SOP
CD74HC173PW	-55 to 125	16 Ld TSSOP
CD74HC173PWR	-55 to 125	16 Ld TSSOP
CD74HC173PWT	-55 to 125	16 Ld TSSOP
CD74HCT173E	-55 to 125	16 Ld PDIP
CD74HCT173M	-55 to 125	16 Ld SOIC
CD74HCT173MT	-55 to 125	16 Ld SOIC
CD74HCT173M96	-55 to 125	16 Ld SOIC

NOTE: When ordering, use the entire part number. The suffixes 96 and R denote tape and reel. The suffix T denotes a small-quantity reel of 250.

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Functional Diagram



TRUTH TABLE

INPUTS				DATA	OUTPUT
MR	CP	DATA ENABLE			
		$\overline{E1}$	$\overline{E2}$	D	Q_n
H	X	X	X	X	L
L	L	X	X	X	Q_0
L	$\uparrow$	H	X	X	Q_0
L	$\uparrow$	X	H	X	Q_0
L	$\uparrow$	L	L	L	L
L	$\uparrow$	L	L	H	H

H= High Voltage Level

L = Low Voltage Level

X= Irrelevant

↑= Transition from Low to High Level

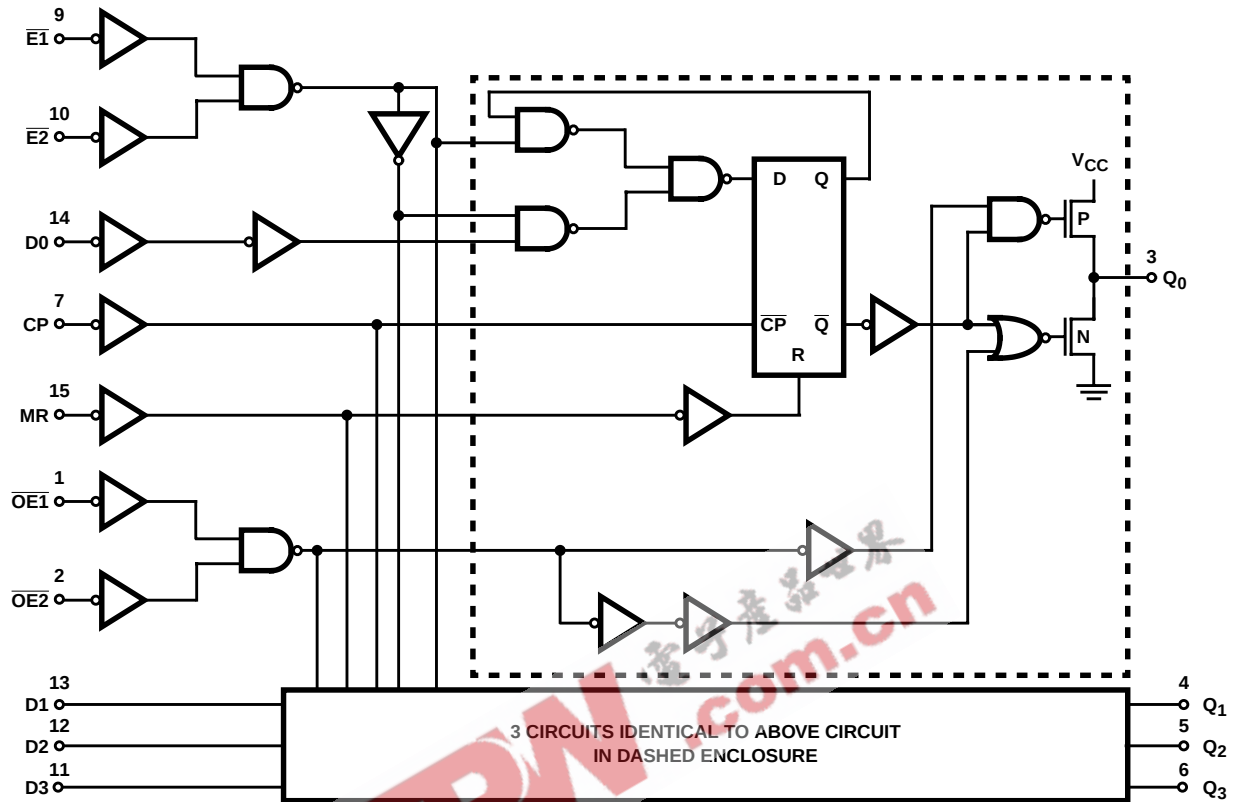
Q_0 = Level Before the Indicated Steady-State Input Conditions Were Established

NOTE:

1. When either OE1 or OE2 (or both) is (are) high, the output is disabled to the high-impedance state, however, sequential operation of the flip-flops is not affected.

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Logic Diagram



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Absolute Maximum Ratings

DC Supply Voltage, V_{CC} -0.5V to 7V
 DC Input Diode Current, I_{IK}
 For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$ $\pm 20mA$
 DC Output Diode Current, I_{OK}
 For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$ $\pm 20mA$
 DC Output Source or Sink Current per Output Pin, I_O
 For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$ $\pm 25mA$
 DC V_{CC} or Ground Current, I_{CC} $\pm 70mA$

Thermal Information

Package Thermal Impedance, θ_{JA} (see Note 2):
 E (PDIP) Package $67^{\circ}C/W$
 M (SOIC) Package $73^{\circ}C/W$
 NS (SOP) Package $64^{\circ}C/W$
 PW (TSSOP) Package $108^{\circ}C/W$
 Maximum Junction Temperature $150^{\circ}C$
 Maximum Storage Temperature Range $-65^{\circ}C$ to $150^{\circ}C$
 Maximum Lead Temperature (Soldering 10s) $300^{\circ}C$
 (SOIC - Lead Tips Only)

Operating Conditions

Temperature Range (T_A) $-55^{\circ}C$ to $125^{\circ}C$
 Supply Voltage Range, V_{CC}
 HC Types 2V to 6V
 HCT Types 4.5V to 5.5V
 DC Input or Output Voltage, V_I , V_O 0V to V_{CC}
 Input Rise and Fall Time
 2V 1000ns (Max)
 4.5V 500ns (Max)
 6V 400ns (Max)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

- The package thermal impedance is calculated in accordance with JESD 51-7.

DC Electrical Specifications

PARAMETER	SYMBOL	TEST CONDITIONS		V _{CC} (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		V _I (V)	I _O (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HC TYPES												
High Level Input Voltage	V _{IH}	-	-	2	1.5	-	-	1.5	-	1.5	-	V
				4.5	3.15	-	-	3.15	-	3.15	-	V
				6	4.2	-	-	4.2	-	4.2	-	V
Low Level Input Voltage	V _{IL}	-	-	2	-	-	0.5	-	0.5	-	0.5	V
				4.5	-	-	1.35	-	1.35	-	1.35	V
				6	-	-	1.8	-	1.8	-	1.8	V
High Level Output Voltage CMOS Loads	V _{OH}	V _{IH} or V _{IL}	-0.02	2	1.9	-	-	1.9	-	1.9	-	V
			-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
			-0.02	6	5.9	-	-	5.9	-	5.9	-	V
High Level Output Voltage TTL Loads	V _{OH}	V _{IH} or V _{IL}	-6	4.5	3.98	-	-	3.84	-	3.7	-	V
			-7.8	6	5.48	-	-	5.34	-	5.2	-	V
Low Level Output Voltage CMOS Loads	V _{OL}	V _{IH} or V _{IL}	0.02	2	-	-	0.1	-	0.1	-	0.1	V
			0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
			0.02	6	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads	V _{OL}	V _{IH} or V _{IL}	6	4.5	-	-	0.26	-	0.33	-	0.4	V
			7.8	6	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I _I	V _{CC} or GND	-	6	-	-	±0.1	-	±1	-	±1	μA
Quiescent Device Current	I _{CC}	V _{CC} or GND	0	6	-	-	8	-	80	-	160	μA

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DC Electrical Specifications (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS		V _{CC} (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		V _I (V)	I _O (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
Three-State Leakage Current	I _{OZ}	V _{IL} or V _{IH}	-	6	-	-	±0.5	-	±0.5	-	±10	μA
HCT TYPES												
High Level Input Voltage	V _{IH}	-	-	4.5 to 5.5	2	-	-	2	-	2	-	V
Low Level Input Voltage	V _{IL}	-	-	4.5 to 5.5	-	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage CMOS Loads	V _{OH}	V _{IH} or V _{IL}	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
High Level Output Voltage TTL Loads			-6	4.5	3.98	-	-	3.84	-	3.7	-	V
Low Level Output Voltage CMOS Loads	V _{OL}	V _{IH} or V _{IL}	0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			6	4.5	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I _I	V _{CC} to GND	0	5.5	-	-	±0.1	-	±1	-	±1	μA
Quiescent Device Current	I _{CC}	V _{CC} or GND	0	5.5	-	-	8	-	80	-	160	μA
Additional Quiescent Device Current Per Input Pin: 1 Unit Load	ΔI _{CC} (Note 3)	V _{CC} -2.1	-	4.5 to 5.5	-	100	360	-	450	-	490	μA
Three-State Leakage Current	I _{OZ}	V _{IL} or V _{IH}	-	5.5	-	-	±0.5	-	±5.0	-	±10	μA

NOTE:

- For dual-supply systems theoretical worst case (V_I = 2.4V, V_{CC} = 5.5V) specification is 1.8mA.

HCT Input Loading Table

INPUT	UNIT LOADS
D0-D3	0.15
$\overline{E1}$ and $\overline{E2}$	0.15
CP	0.25
MR	0.2
$\overline{OE1}$ and $\overline{OE2}$	0.5

NOTE: Unit Load is ΔI_{CC} limit specified in DC Electrical Specifications table, e.g., 360μA max at 25°C.

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Switching Specifications Input $t_r, t_f = 6\text{ns}$

PARAMETER	SYMBOL	TEST CONDITIONS	V _{CC} (V)	25°C		-40°C TO 85°C	-55°C TO 125°C	UNITS
				TYP	MAX	MAX	MAX	
HC TYPES								
Propagation Delay, Clock to Output	t _{PLH} , t _{PHL}	C _L = 50pF	2	-	200	250	300	ns
			4.5	-	40	50	60	ns
		C _L = 15pF	5	17	-	-	-	ns
		CL = 50pF	6	-	34	43	51	ns
Propagation Delay, MR to Output	t _{PHL}	C _L = 50pF	2	-	175	220	265	ns
			4.5	-	35	44	53	ns
		C _L = 15pF	5	12	-	-	-	ns
		CL = 50pF	6	-	30	37	45	ns
Propagation Delay Output Enable to Q (Figure 6)	t _{PLZ} , t _{PHZ} t _{PZL} , t _{PZH}	CL = 50pF	2		150	190	225	ns
		C _L = 50pF	4.5		30	38	45	ns
		C _L = 15pF	5	12	-	-	-	ns
		CL = 50pF	6		26	33	38	ns
Output Transition Times	t _{TLH} , t _{THL}	C _L = 50pF	2	-	60	75	90	ns
			4.5	-	12	15	18	ns
			6	-	10	13	15	ns
Maximum Clock Frequency	f _{MAX}	C _L = 15pF	5	60	-	-	-	MHz
Input Capacitance	C _{IN}	-	-	-	10	10	10	pF
Three-State Output Capacitance	C _O	-	-	-	10	10	10	pF
Power Dissipation Capacitance (Notes 4, 5)	C _{PD}	-	5	29	-	-	-	pF
HCT TYPES								
Propagation Delay, Clock to Output	t _{PLH} , t _{PHL}	C _L = 50pF	4.5	-	40	50	60	ns
		C _L = 15pF	5	17	-	-	-	ns
Propagation Delay, MR to Output	t _{PHL}	C _L = 50pF	4.5	-	44	55	66	ns
		C _L = 15pF	5	18	-	-	-	ns
Propagation Delay Output Enable to Q (Figure 6)	t _{PZL} , t _{PZH}	CL = 50pF	2		150	190	225	ns
		C _L = 50pF	4.5		30	38	45	ns
		C _L = 15pF	5	14	-	-	-	ns
		CL = 50pF	6		26	33	38	ns
Output Transition Times	t _{TLH} , t _{THL}	C _L = 50pF	4.5	-	15	19	22	ns
Maximum Clock Frequency	f _{MAX}	C _L = 15pF	5	60	-	-	-	MHz
Input Capacitance	C _{IN}	-	-	-	10	10	10	pF
Power Dissipation Capacitance (Notes 4, 5)	C _{PD}	-	5	34	-	-	-	pF

NOTES:

- C_{PD} is used to determine the dynamic power consumption, per package.
- $P_D = V_{CC}^2 f_i + \sum (C_L V_{CC}^2 + f_O)$ where f_i = Input Frequency, f_O = Output Frequency, C_L = Output Load Capacitance, V_{CC} = Supply Voltage.

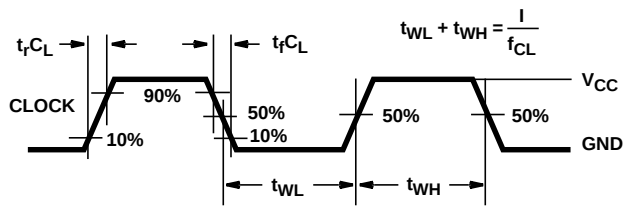
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Prerequisite For Switching Specifications

PARAMETER	SYMBOL	V _{CC} (V)	25°C		-40°C TO 85°C		-55°C TO 125°C		UNITS
			MIN	MAX	MIN	MAX	MIN	MAX	
HC TYPES									
Maximum Clock Frequency	f _{MAX}	2	6	-	5	-	4	-	MHz
		4.5	30	-	24	-	20	-	MHz
		6	35	-	28	-	24	-	MHz
MR Pulse Width	t _w	2	80	-	100	-	120	-	ns
		4.5	16	-	20	-	24	-	ns
		6	14	-	17	-	20	-	ns
Clock Pulse Width	t _w	2	80	-	100	-	120	-	ns
		4.5	16	-	20	-	24	-	ns
		6	14	-	17	-	20	-	ns
Set-up Time, Data to Clock and $\bar{E}$ to Clock	t _{SU}	2	60	-	75	-	90	-	ns
		4.5	12	-	15	-	18	-	ns
		6	10	-	13	-	15	-	ns
Hold Time, Data to Clock	t _H	2	3	-	3	-	3	-	ns
		4.5	3	-	3	-	3	-	ns
		6	3	-	3	-	3	-	ns
Hold Time, $\bar{E}$ to Clock	t _H	2	0	-	0	-	0	-	ns
		4.5	0	-	0	-	0	-	ns
		6	0	-	0	-	0	-	ns
Removal Time, MR to Clock	t _{REM}	2	60	-	75	-	90	-	ns
		4.5	12	-	15	-	18	-	ns
		6	10	-	13	-	15	-	ns
HCT TYPES									
Maximum Clock Frequency	f _{MAX}	4.5	20	-	16	-	13	-	MHz
MR Pulse Width	t _w	4.5	15	-	19	-	22	-	ns
Clock Pulse Width	t _w	4.5	25	-	31	-	38	-	ns
Set-up Time, $\bar{E}$ to Clock	t _{SU}	4.5	12	-	15	-	18	-	ns
Set-up Time, Data to Clock	t _{SU}	4.5	18	-	23	-	27	-	ns
Hold Time, Data to Clock	t _H	4.5	0	-	0	-	0	-	ns
Hold Time, $\bar{E}$ to Clock	t _H	4.5	0	-	0	-	0	-	ns
Removal Time, MR to Clock	t _{REM}	4.5	12	-	15	-	18	-	ns

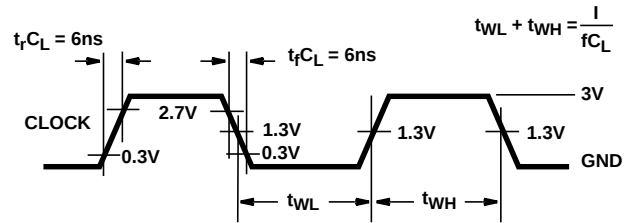
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Test Circuits and Waveforms



NOTE: Outputs should be switching from 10% V_{CC} to 90% V_{CC} in accordance with device truth table. For f_{MAX} , input duty cycle = 50%.

FIGURE 1. HC CLOCK PULSE RISE AND FALL TIMES AND PULSE WIDTH



NOTE: Outputs should be switching from 10% V_{CC} to 90% V_{CC} in accordance with device truth table. For f_{MAX} , input duty cycle = 50%.

FIGURE 2. HCT CLOCK PULSE RISE AND FALL TIMES AND PULSE WIDTH

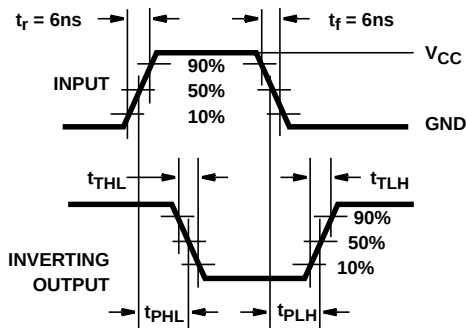


FIGURE 3. HC AND HCU TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

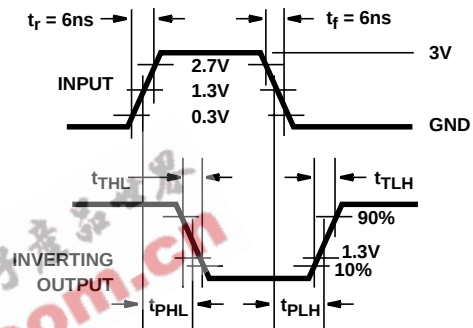


FIGURE 4. HCT TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

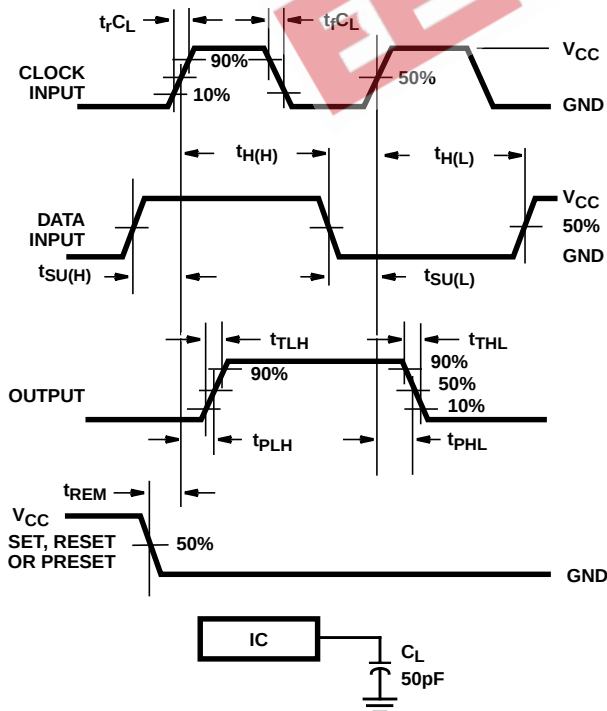


FIGURE 5. HC SETUP TIMES, HOLD TIMES, REMOVAL TIME, AND PROPAGATION DELAY TIMES FOR EDGE TRIGGERED SEQUENTIAL LOGIC CIRCUITS

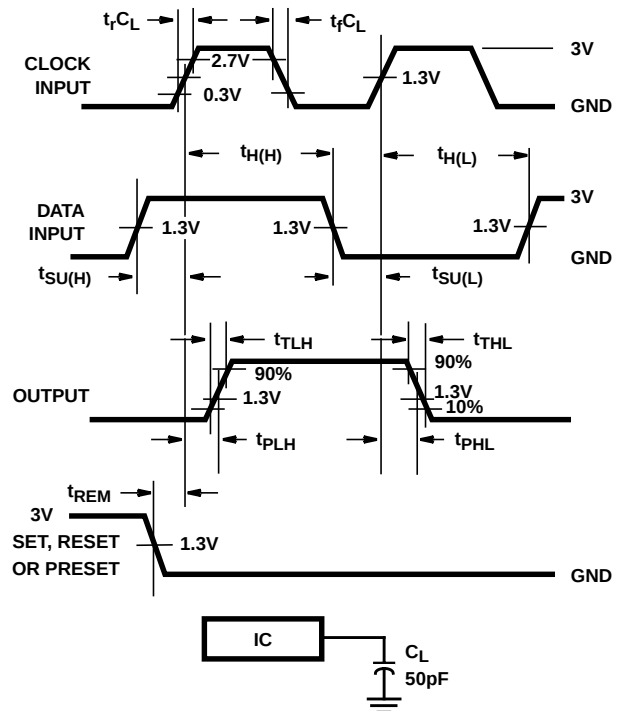


FIGURE 6. HCT SETUP TIMES, HOLD TIMES, REMOVAL TIME, AND PROPAGATION DELAY TIMES FOR EDGE TRIGGERED SEQUENTIAL LOGIC CIRCUITS

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Test Circuits and Waveforms (Continued)

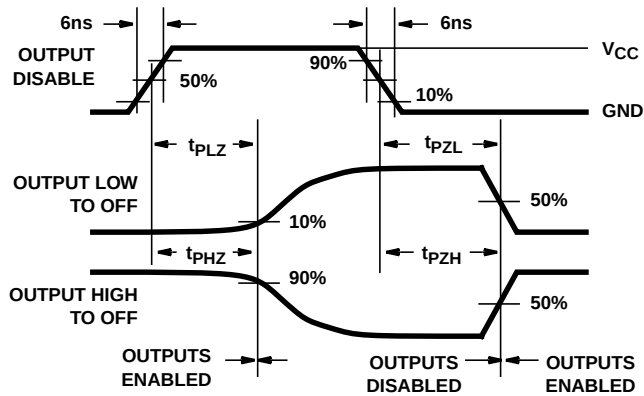


FIGURE 7. HC THREE-STATE PROPAGATION DELAY WAVEFORM

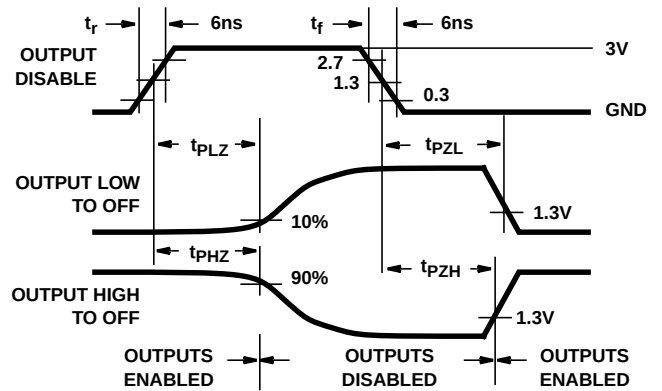
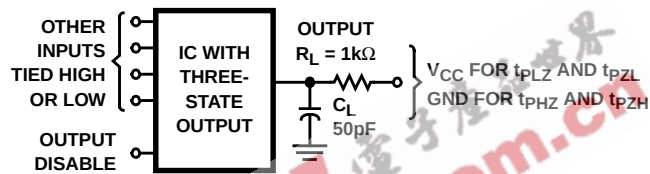


FIGURE 8. HCT THREE-STATE PROPAGATION DELAY WAVEFORM



NOTE: Open drain waveforms t_{PLZ} and t_{PZL} are the same as those for three-state shown on the left. The test circuit is Output $R_L = 1k\Omega$ to V_{CC} , $C_L = 50pF$.

FIGURE 9. HC AND HCT THREE-STATE PROPAGATION DELAY TEST CIRCUIT

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-8682501EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
5962-8875901EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
CD54HC173F	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
CD54HC173F3A	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
CD54HCT173F3A	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
CD74HC173E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74HC173EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74HC173M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC173M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC173M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC173M96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC173ME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC173MG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC173MT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC173MTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC173MTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC173NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC173NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC173NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC173PW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC173PWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC173PWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC173PWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC173PWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC173PWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC173PWT	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC173PWTE4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
CD74HC173PWTG4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT173E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74HCT173EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74HCT173M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT173M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT173M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT173M96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT173ME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT173MG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT173MT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT173MTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT173MTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

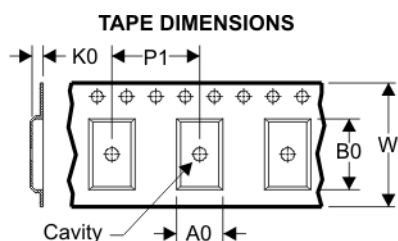
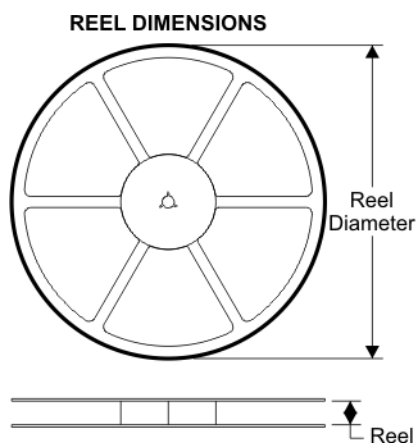
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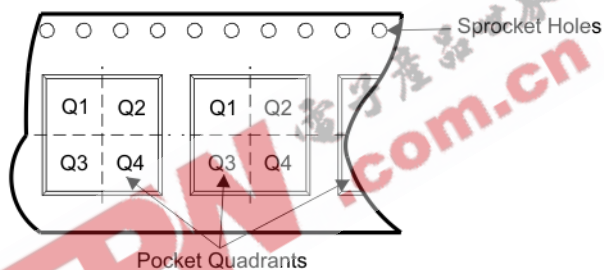
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TAPE AND REEL BOX INFORMATION



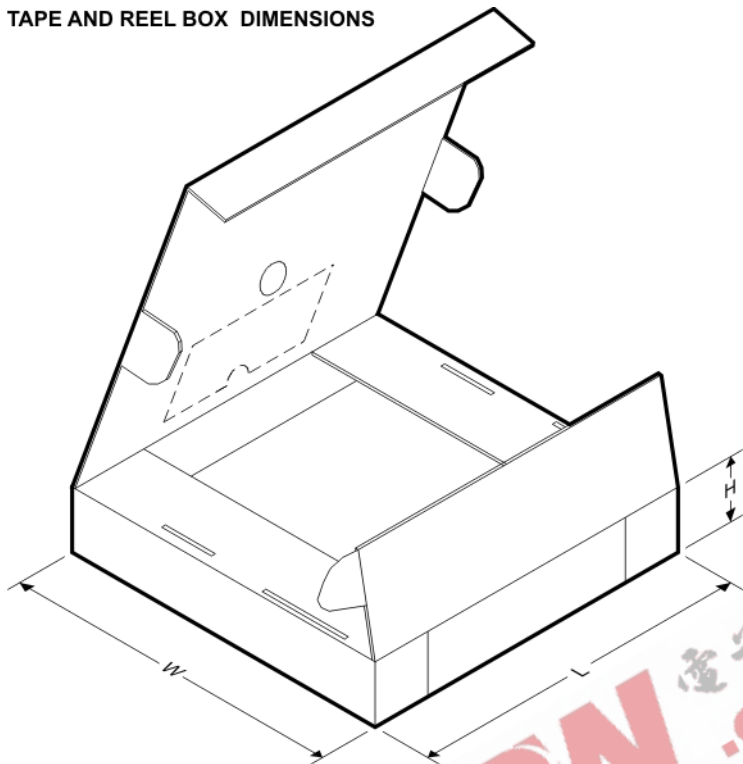
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HC173M96	D	16	SITE 27	330	16	6.5	10.3	2.1	8	16	Q1
CD74HC173NSR	NS	16	SITE 41	330	16	8.2	10.5	2.5	12	16	Q1
CD74HC173PWR	PW	16	SITE 41	330	12	7.0	5.6	1.6	8	12	Q1
CD74HCT173M96	D	16	SITE 27	330	16	6.5	10.3	2.1	8	16	Q1

TAPE AND REEL BOX DIMENSIONS

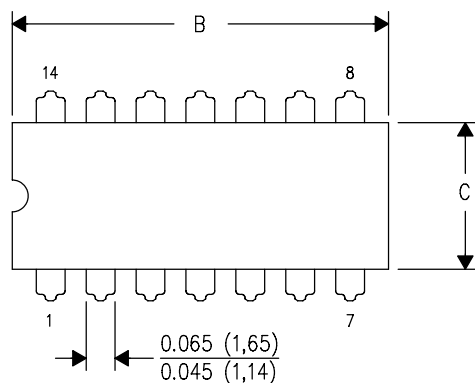


Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
CD74HC173M96	D	16	SITE 27	342.9	336.6	28.58
CD74HC173NSR	NS	16	SITE 41	346.0	346.0	33.0
CD74HC173PWR	PW	16	SITE 41	346.0	346.0	29.0
CD74HCT173M96	D	16	SITE 27	342.9	336.6	28.58

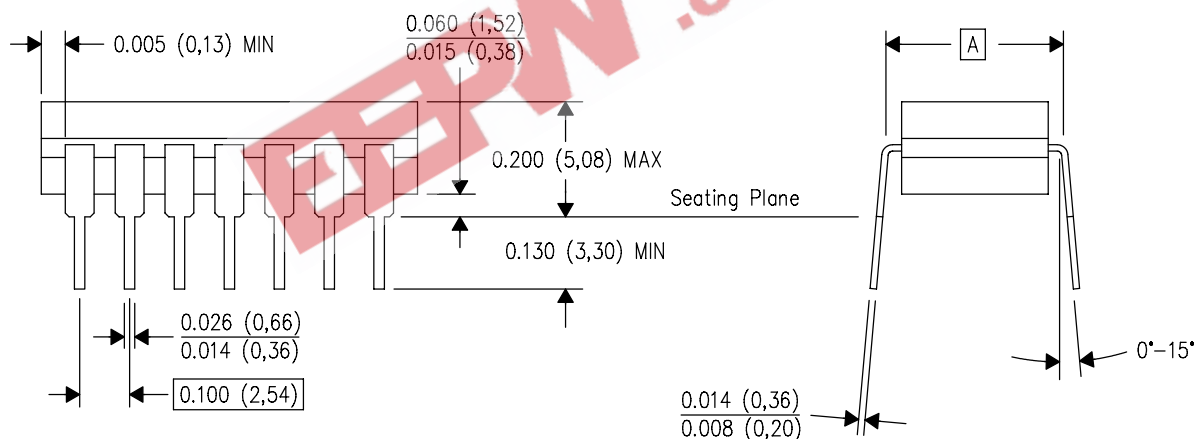
J (R—GDIP—T**) (R—GDIP—T**)

14 LEADS SHOWN

CERAMIC DUAL IN—LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

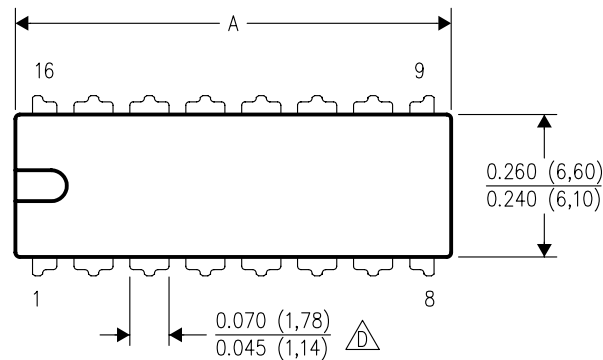
- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1—T14, GDIP1—T16, GDIP1—T18 and GDIP1—T20.

MECHANICAL DATA

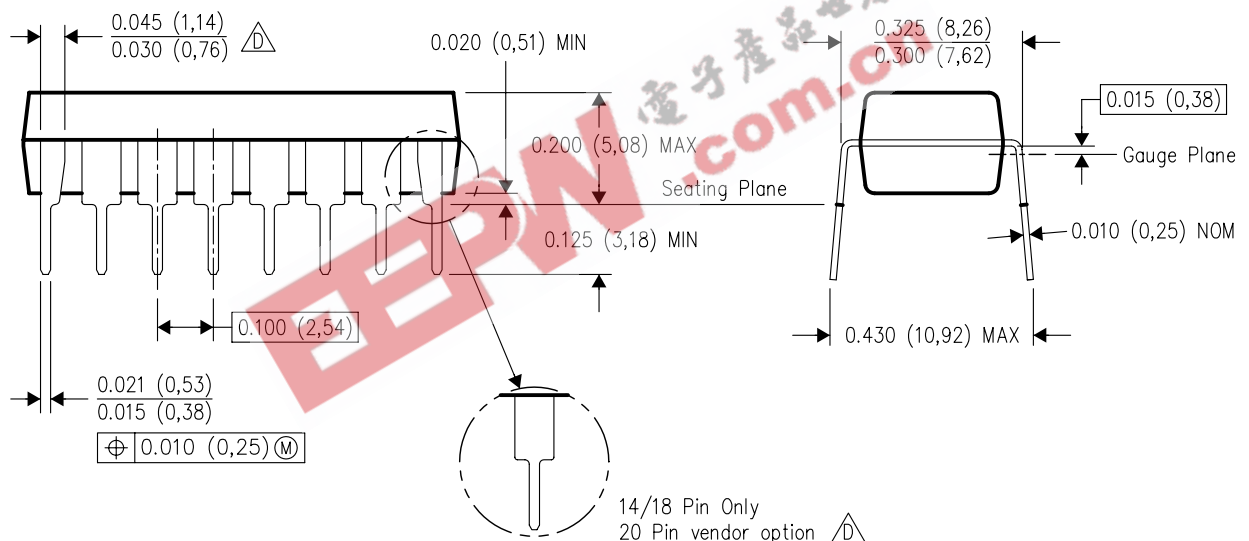
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



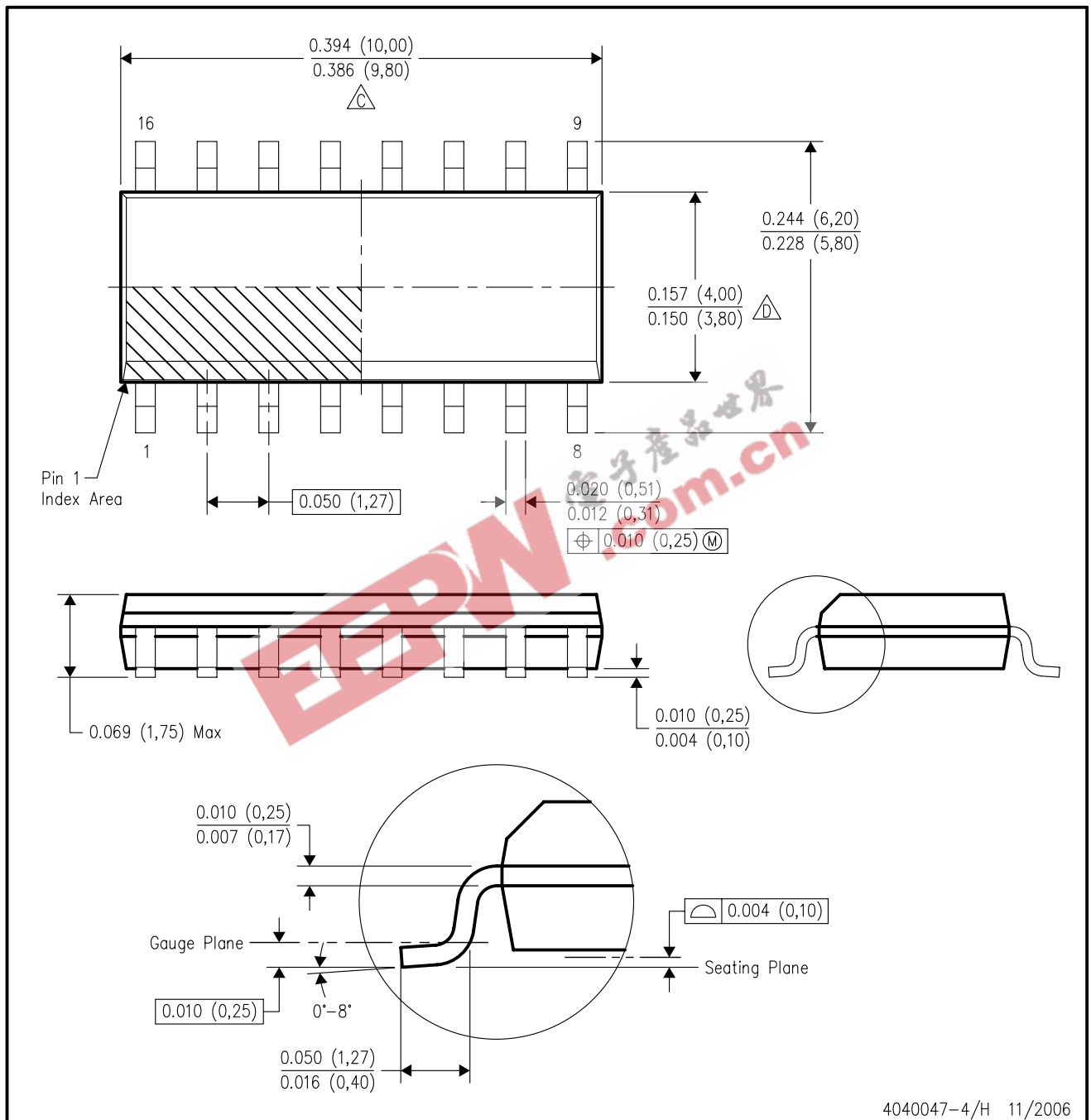
4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

MECHANICAL DATA

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



4040047-4/H 11/2006

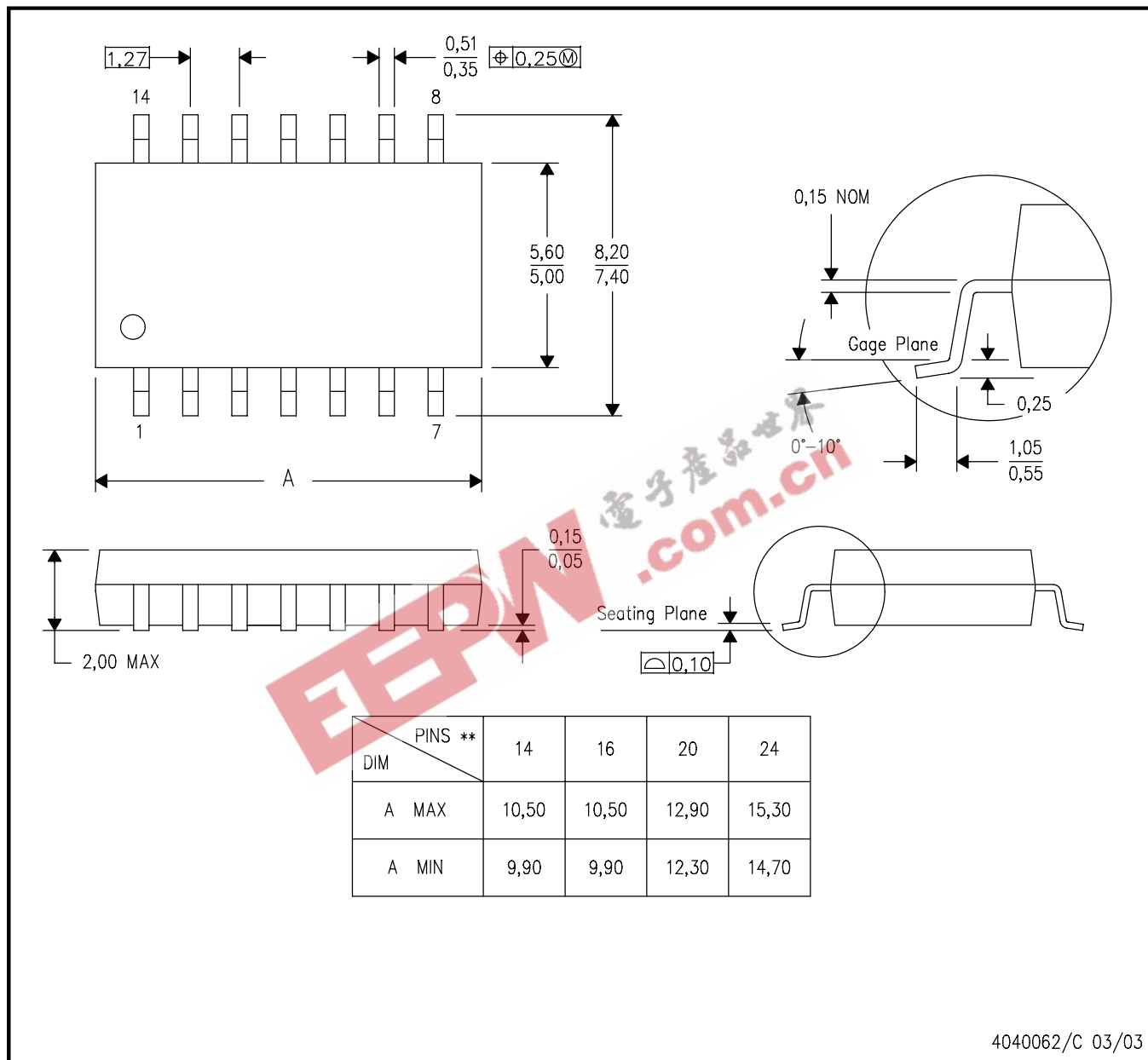
- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AC.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

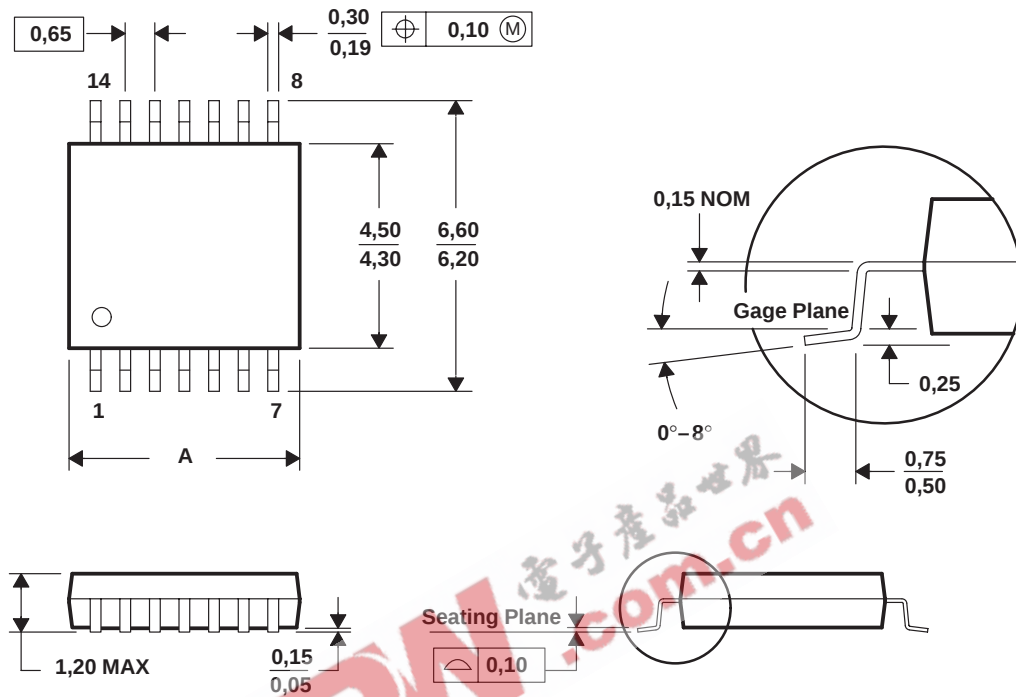
MECHANICAL DATA

MTSS001C – JANUARY 1995 – REVISED FEBRUARY 1999

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



	PINS **	8	14	16	20	24	28
DIM							
A MAX		3,10	5,10	5,10	6,60	7,90	9,80
A MIN		2,90	4,90	4,90	6,40	7,70	9,60

4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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